



Pre applied high performance thermal paste (silicone based)

TP(HPTP)SEMITOP_E1

Features*

- New high performance thermal paste
- Superior heat dissipation
- Inhomogeneous honeycomb structure
- Optimized thickness of thermal paste layer
- High process reliability due to automated screen printing process

Characteristics		Symbol	Conditions	min.	typ.	max.	Unit
Characteristics of printing process							
W_{tp}	material weight			140	170	200	mg
Storage conditions							
t_{stg}	storage time				12		month
T_{stg}	storage temperature			5	40		°C
RH_{stg}	storage humidity			10		85	%
TIM material characteristic							
γ_{tp}	specific gravity			4.2			g/cm³
R_{tp}	resistivity			1.2*10¹²			Ω/cm
E_{tp}	dielectric strength			3			kV/mm
λ_{tp}	thermal conductivity				2.5		W/(mK)

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honeycomb structure